

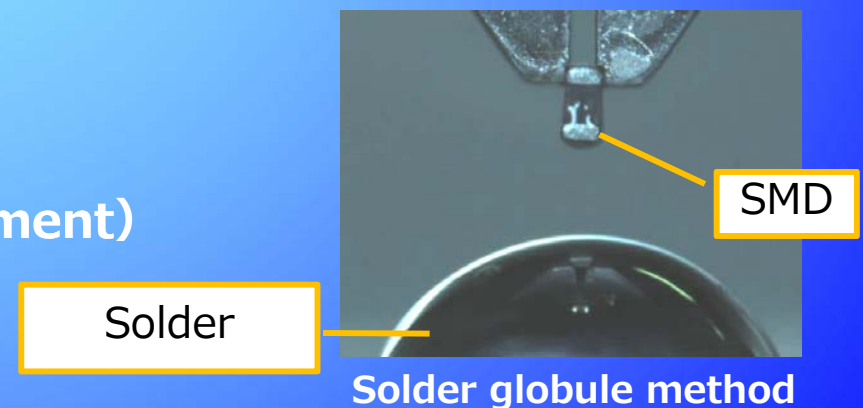
Solderability testing standardization group

◆ Target / Scope

- Standardization of evaluation testing of solderability for electrode terminals of electronic components and soldering heat resistance.
 - Maintenance of existing standards for solder testing (IEC standards, JIS, JEITA standards)
 - Proposal and verification of standardization for new solder testing methods

◆ Summary of activity

- We are targeting on standardizing the test method which can quantify the solderability test.
- For the international standardization, we are participating in TC 91/WG 3 and working on establishment and revision of IEC standards.
- Standard revision condition
 - Revision of JIS C 60068-2-20
 - Revision of JIS C 60068-2-69 (Amendment)
 - Revision of JEITA ET-7411



◆ Standards that we are working on

IEC Standard	Correspondent JIS	JEITA Standard	Title
IEC 60068-2-20 (Under review)	JIS C 60068-2-20	—	Environmental testing - Part 2-20: Tests - Test T: Test methods for solderability and resistance to soldering heat of devices with leads
IEC 60068-2-58	JIS C 60068-2-58	—	Environmental testing - Part 2-58: Tests - Test Td: Test methods for solderability, resistance to dissolution of metallization and to soldering heat of surface mounting devices (SMD)
IEC 60068-2-69	JIS C 60068-2-69	(ET-7411)	Environmental testing - Part 2-69: Tests - Test Te/Tc: Solderability testing of electronic components and printed boards by the wetting balance (force measurement) method
IEC 60068-2-83	JIS C 60068-2-83	(ET-7404)	Environmental testing - Part 2-83: Tests - Test Tf: Solderability testing of electronic components for surface mounting devices (SMD) by the wetting balance method using solder paste

◆ Standards that we are working on

IEC Standard	Correspondent JIS	JEITA Standard	Title
IEC/TR 60068-3-12	—	—	Environmental testing - Part 3-12: Supporting documentation and guidance - Method to evaluate a possible lead-free solder reflow temperature profile
IEC 60068-3-13	JIS C 60068-3-13	—	Environmental testing - Part 3-13: Supporting documentation and guidance on Test T - Soldering